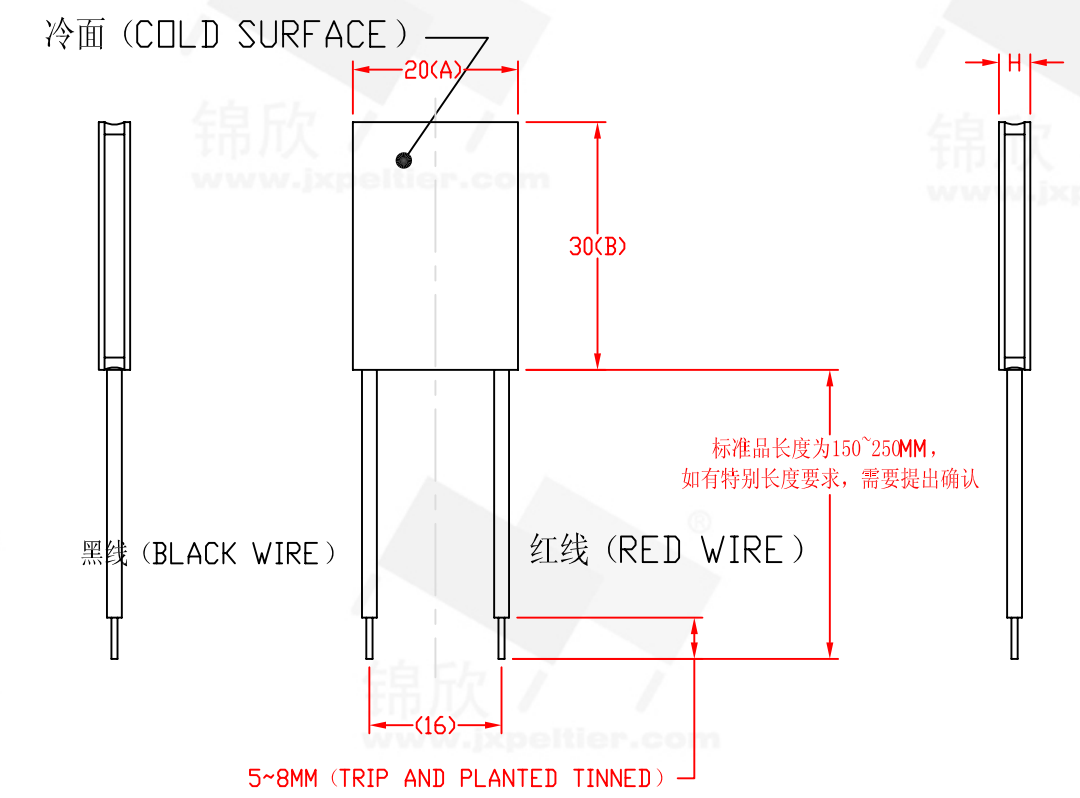


REVISIONS						
REV.	POS.	DESCRIPTION	DATE	DRW	APP	ECN#
A		INITIAL CREATION	2008/03/12	GARY	JUNSON	



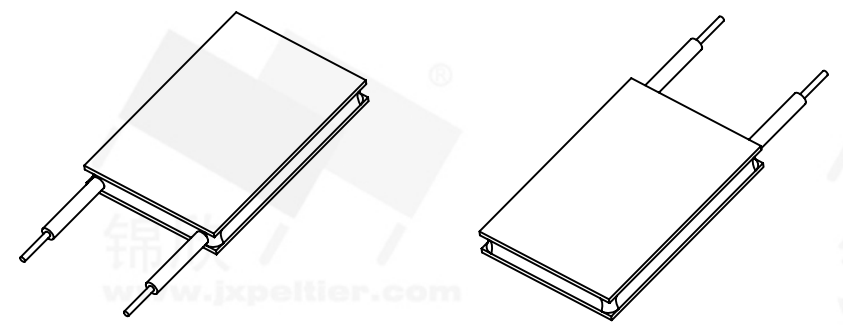
**TEC 1 - 047 XX 20 30**

热致冷组件    陶瓷结构式    级数    电堆数    最大电流    外形尺寸(A)    外形尺寸(B)

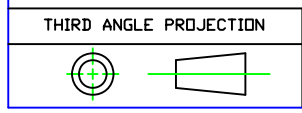
**注意事项:**

1. 半导体致冷片总成厚度公差为±0.2, 客户在和散热片组装时, 需要考量此公差带, 不得压得太紧, 也不能压得太松, 否则会导致半导体致冷片破裂或降低功效。
2. 半导体致冷片在通电前, 检查是否有安装符合要求当量的散热片, 禁止空载, 否则会因工作所产生热源没有传递走而烧坏。
3. 标准的半导体致冷片型号及规格参数如下列表 (如有更改, 不另行通知, 非标规格需要定制, 请联络销售部):

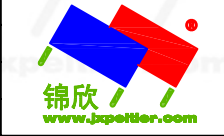
序号	型号	电堆数	最大电流	最大电压	最大冷量(W)	最大温差(°C)	外形尺寸(MM)			电阻	重量
ITEM	PART NUMBER	COUPLES	A (MAX)	V (MAX)	室温环境TH=27°		A	B	H 实物为准	Ω	g
1	TEC1-047032030	047	3	5.6	10.5	66	20	30	4.4	--	--
2	TEC1-047042030		4		13.9	66	20	30	3.5	--	--
3	TEC1-047052030		5		17.4	66	20	30	3.3	--	--
4	TEC1-047062030		6		20.9	66	20	30	3.1	--	--



\*DO NOT SCALE DRAWING



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USED OR DISCLOSED OR IN PART TO ANYONE WITHOUT THE PERMISSION OF JXPELTIER (SUZHOU)  
CO., LTD.

1. UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE MM 2. TOLERANCE ARE AS FOLLOWS: 0 < X < 2 ± 0.06 2 < X < 10 ± 0.08 10 < X < 50 ± 0.12 50 < X < 100 ± 0.16 100 < X < 200 ± 0.20 200 < X < 300 ± 0.30 ANGLES ± 0.5°	Part NO.	TEC1-047xx2030	DESCRIPTION	DC 5.6V(Max), 3~5A, 047晶堆, 单层, 冷端20x30, 热端20x30mm		
	SIGNATURE		DATE		 锦欣制冷 (苏州) 有限公司 <b>JXPELTIER (SUZHOU) CO., LTD</b> Tel/Fax: +86-512-62539286    Mobile: +86-18061938176 emailto: jxpeltier@gmail.com    http://www.jxpeltier.com	
	DRAWN BY	GARY	2008/03/12			
	CHECKED BY	JACK	2008/03/12			
	ENGR	VIVI	2008/03/12			
APPROVED BY	JASON	2008/03/12				
MATERIAL:	ISSUED BY	LILY	2008/03/12	CAD DWG:	CAD MDDLE:	
				SCALE: 1:1	REV: A	
				SIZE: A3	SHEET: 1 OF 1	